# 2N5457, 2N5458

**Preferred Device** 

## **JFETs - General Purpose**

### **N-Channel - Depletion**

N-Channel Junction Field Effect Transistors, depletion mode (Type A) designed for audio and switching applications.

### **Features**

- N-Channel for Higher Gain
- Drain and Source Interchangeable
- High AC Input Impedance
- High DC Input Resistance
- Low Transfer and Input Capacitance
- Low Cross-Modulation and Intermodulation Distortion
- Unibloc Plastic Encapsulated Package
- Pb-Free Packages are Available\*

### **MAXIMUM RATINGS**

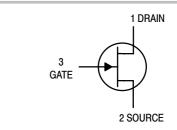
Rating	Symbol	Value	Unit
Drain-Source Voltage	V <sub>DS</sub>	25	Vdc
Drain-Gate Voltage	$V_{DG}$	25	Vdc
Reverse Gate – Source Voltage	$V_{GSR}$	-25	Vdc
Gate Current	I <sub>G</sub>	10	mAdc
Total Device Dissipation @ T <sub>A</sub> = 25°C Derate above 25°C	P <sub>D</sub>	310 2.82	mW mW/°C
Operating Junction Temperature	TJ	135	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.



### ON Semiconductor®

### http://onsemi.com



### MARKING DIAGRAM



TO-92 CASE 29 STYLE 5



2N545x = Device Code

x = 7 or 8

A = Assembly Location

Y = Year
WW = Work Week
= Pb-Free Package

(Note: Microdot may be in either location)

### **ORDERING INFORMATION**

Device	Package	Shipping
2N5457	TO-92	1000 Units/Box
2N5457G	TO-92 (Pb-Free)	1000 Units/Box
2N5458	TO-92	1000 Units/Box
2N5458G	TO-92 (Pb-Free)	1000 Units/Box

**Preferred** devices are recommended choices for future use and best overall value.

<sup>\*</sup>For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

### 2N5457, 2N5458

### **ELECTRICAL CHARACTERISTICS** ( $T_A = 25^{\circ}C$ unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS			•			
Gate – Source Breakdown Voltage ( $I_G = -10 \mu Adc$ , $V_{DS} = 0$ )		V <sub>(BR)GSS</sub>	-25	_	_	Vdc
Gate Reverse Current $  (V_{GS} = -15 \text{ Vdc}, V_{DS} = 0) $ $  (V_{GS} = -15 \text{ Vdc}, V_{DS} = 0, T_A = 100^{\circ}\text{C}) $		l <sub>GSS</sub>	_ _	_ _	-1.0 -200	nAdc
Gate-Source Cutoff Voltage (V <sub>DS</sub> = 15 Vdc, i <sub>D</sub> = 10 nAdc)	2N5457 2N5458	V <sub>GS(off)</sub>	-0.5 -1.0	- -	-6.0 -7.0	Vdc
Gate–Source Voltage ( $V_{DS}$ = 15 Vdc, $i_D$ = 100 μAdc) ( $V_{DS}$ = 15 Vdc, $i_D$ = 200 μAdc)	2N5457 2N5458	V <sub>GS</sub>	_ _	-2.5 -3.5	- -	Vdc
ON CHARACTERISTICS						
Zero-Gate-Voltage Drain Current (Note 1) (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0)	2N5457 2N5458	I <sub>DSS</sub>	1.0 2.0	3.0 6.0	5.0 9.0	mAdc
DYNAMIC CHARACTERISTICS						
Forward Transfer Admittance (Note 1) (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0, f = 1 kHz)	2N5457 2N5458	Y <sub>fs</sub>	1000 1500	3000 4000	5000 5500	μmhos
Output Admittance Common Source (Note 1) (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0, f = 1 kHz)		Y <sub>os</sub>	_	10	50	μmhos
Input Capacitance (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0, f = 1 kHz)		C <sub>iss</sub>	_	4.5	7.0	pF
Reverse Transfer Capacitance (V <sub>DS</sub> = 15 Vdc, V <sub>GS</sub> = 0, f = 1 kHz)		C <sub>rss</sub>	_	1.5	3.0	pF

Pulse Width ≤ 630 ms, Duty Cycle ≤ 10%.

# TYPICAL CHARACTERISTICS For 2N5457 Only

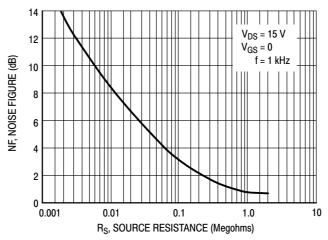


Figure 1. Noise Figure versus Source Resistance

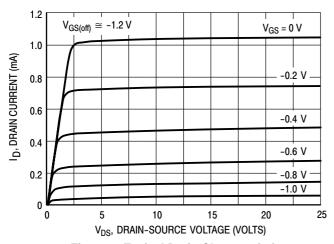
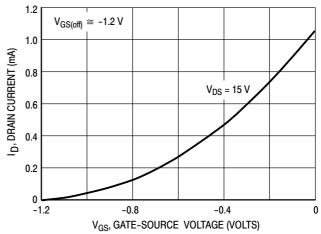


Figure 2. Typical Drain Characteristics



**Figure 3. Common Source Transfer Characteristics** 

### TYPICAL CHARACTERISTICS For 2N5457 Only

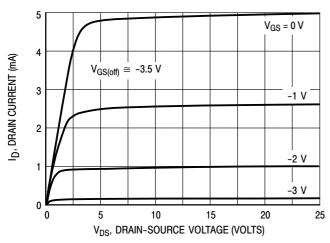


Figure 4. Typical Drain Characteristics

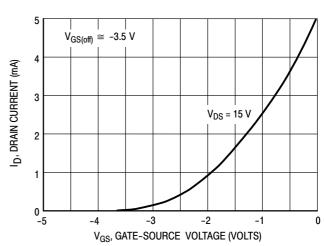


Figure 5. Common Source Transfer Characteristics

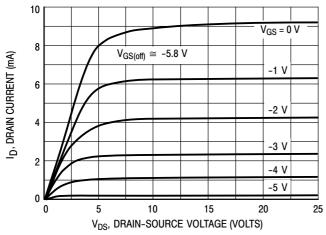


Figure 6. Typical Drain Characteristics

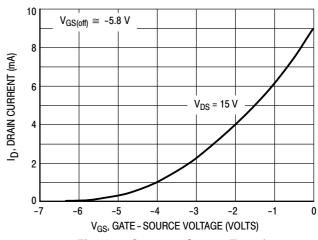
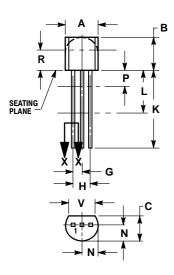


Figure 7. Common Source Transfer Characteristics

NOTE: Note: Graphical data is presented for dc conditions. Tabular data is given for pulsed conditions (Pulse Width = 630 ms, Duty Cycle = 10%). Under dc conditions, self heating in higher  $I_{DSS}$  units reduces  $I_{DSS}$ .

### PACKAGE DIMENSIONS

### TO-92 (TO-226) CASE 29-11 ISSUE AI





#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI
   VIA EM 1092
- Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
- 3. CONTOUR OF PACKAGE BEYOND DIMENSION R IS UNCONTROLLED.
- 4. LEAD DIMENSION IS UNCONTROLLED IN P AND BEYOND DIMENSION K MINIMUM.

	INCHES		MILLIMETERS	
DIM	MIN	MAX	MIN	MAX
Α	0.175	0.205	4.45	5.20
В	0.170	0.210	4.32	5.33
С	0.125	0.165	3.18	4.19
D	0.016	0.021	0.407	0.533
G	0.045	0.055	1.15	1.39
Н	0.095	0.105	2.42	2.66
J	0.015	0.020	0.39	0.50
K	0.500		12.70	
L	0.250		6.35	
N	0.080	0.105	2.04	2.66
Р		0.100		2.54
R	0.115		2.93	
V	0.135		3.43	

TYLE 5: PIN 1. DRAIN 2 SOUR

2. SOURCE 3. GATE

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 61312, Phoenix, Arizona 85082–1312 USA Phone: 480–829–7710 or 800–344–3860 Toll Free USA/Canada Fax: 480–829–7709 or 800–344–3867 Toll Free USA/Canada Email: orderlit@onsemi.com

N. American Technical Support: 800–282–9855 Toll Free USA/Canada

Japan: ON Semiconductor, Japan Customer Focus Center 2–9–1 Kamimeguro, Meguro–ku, Tokyo, Japan 153–0051 Phone: 81–3–5773–3850

ON Semiconductor Website: http://onsemi.com

Order Literature: http://www.onsemi.com/litorder

For additional information, please contact your local Sales Representative.